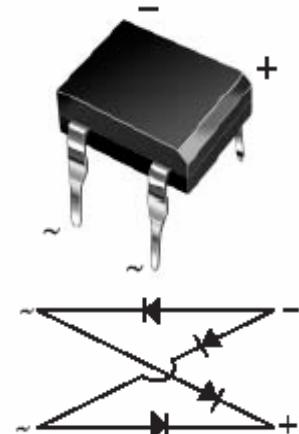


Features

- Ideal for automated placement
- Applicable for automatic insertion
- High surge current capability
- Solder Dip 260°C, 10 seconds

Package: DFM



Mechanical Data

- Case:DFM
- Epoxy meets UL-94V-0 Flammability rating
- Terminals: Matte tin plated leads, solderable per J-STD-002B and JESD22-B102D
- Polarity: As marked on body

Schematic Diagram

Typical Applications

General purpose use in AC-to-DC bridge full wave rectifications for SMPS, Lighting Ballasters, Adapters, Battery Chargers, Home Appliances, Office Equipment and Telecommunication applications.

Maximum Ratings & Electrical Characteristics

($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	DB151	DB152	DB153	DB154	DB155	DB156	DB157	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Output Rectified Current at $T_A=40^\circ\text{C}$	$I_{F(AV)}$	1.5						A	
Peak Forward Surge Current Single Sine-Wave Superimposed on Rated Load (JEDEC Method)	I_{FSM}	50						A	
Rating for Fusible ($t<8.3\text{ms}$)	I^2t	10						A^2sec	
Maximum Instantaneous Forward Voltage Drop per Leg at 1.5A	V_F	1.10						V	
Maximum DC Reverse Current at $T_A=25^\circ\text{C}$	I_R	5						μA	
Rated DC Blocking Voltage per Leg $T_A=125^\circ\text{C}$		500							
Typical Junction Capacitance per Element at $4.0\text{V}, 1\text{MHz}$	C_J	16						pF	
Typical Thermal Resistance per Leg (Note 1)	$R_{\theta JA}$	40						$^\circ\text{C}/\text{W}$	
	$R_{\theta JL}$	15							
Operating Junction Temperature Range	T_J	-55 to +150						$^\circ\text{C}$	
Storage Temperature Range	T_{STG}	-55 to +150						$^\circ\text{C}$	

Notes: 1. Device mounted P.C.B with 0.47x0.47"(12mmx12mm) Copper Pads.

2. JEDEC registered values

Ratings and Characteristics Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

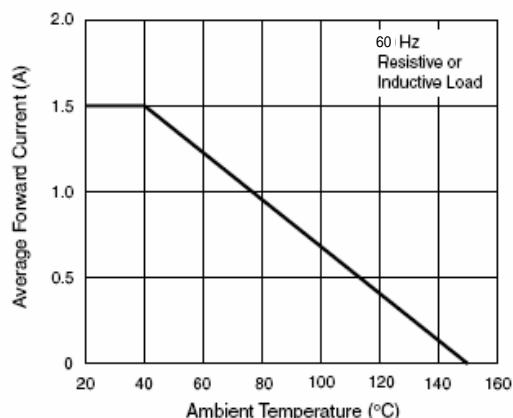


Figure 1. Forward Current Derating Curve Per Diode

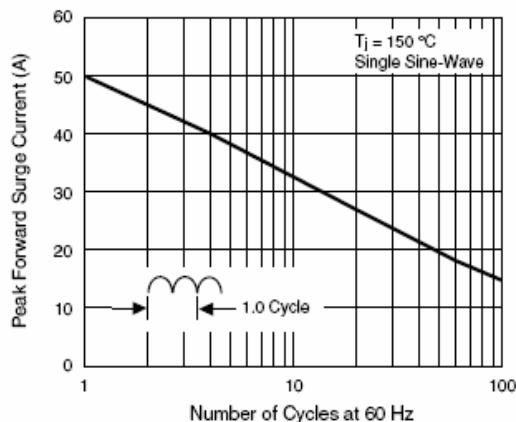


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current Per Diode

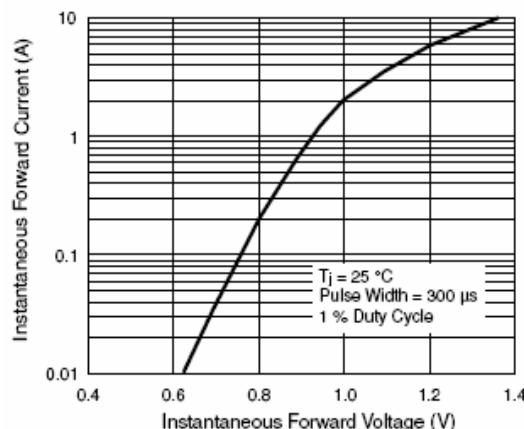


Figure 3. Typical Forward Characteristics Per Diode

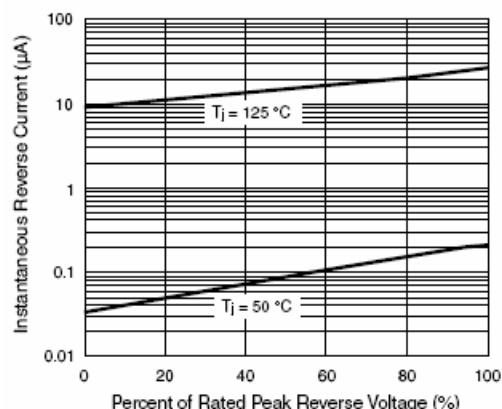


Figure 4. Typical Reverse Leakage Characteristics Per Diode

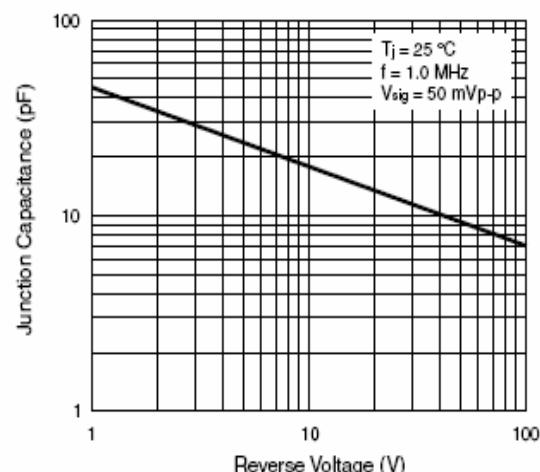


Figure 5. Typical Junction Capacitance Per Diode

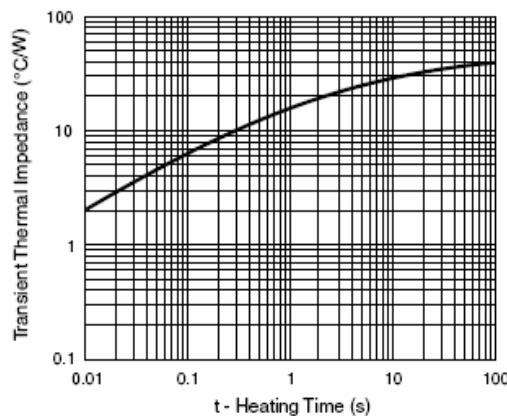
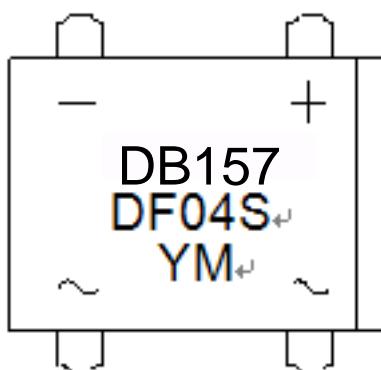


Figure 6. Typical Transient Thermal Impedance

Marking



DATE CODE

Year	2009	2010	2011	2012	2013	2014	2015	2016	2017	2018	2019	2020
Code	9	A	B	C	D	E	F	G	H	J	K	0
Month	1	2	3	4	5	6	7	8	9	10	11	12
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions

